

## **40V N-Channel Enhancement Mode Power MOSFET**

## **Description**

WMO75N04T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

### **Features**

- $V_{DS}$ = 40V,  $I_D$  = 75A  $R_{DS(on)}$  < 6.6m $\Omega$  @  $V_{GS}$  = 10V  $R_{DS(on)}$  < 8.8m $\Omega$  @  $V_{GS}$  = 4.5V
- Low Gate Charge
- Low R<sub>DS(ON)</sub>
- 100% EAS Guaranteed

# **Applications**

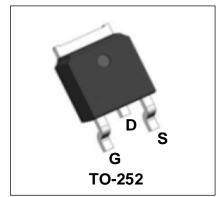
- Power Management Switches
- DC/DC Converter

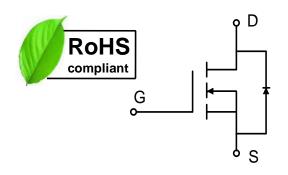
## **Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DS</sub>	40	V	
Gate-Source Voltage	V <sub>GS</sub>	±20	V	
Outine Dais Out 1	T <sub>C</sub> =25°C	lο	75	A
Continuous Drain Current <sup>1</sup>	T <sub>C</sub> =100°C		45	
Pulsed Drain Current <sup>2</sup>	I <sub>DM</sub>	161	Α	
Single Pulse Avalanche Energy <sup>3</sup>	EAS	88	mJ	
Avalanche Current	las	42	Α	
Total Power Dissipation <sup>4</sup> T <sub>C</sub> =25°C		P <sub>D</sub>	44.6	W
Operating Junction and Storage Temperature Range	•	TJ, TSTG	-55 to 150	°C

### **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	Reja	75	°C/W
Thermal Resistance from Junction-to-Case <sup>1</sup>	R <sub>θ</sub> Jc	2.8	°C/W







### Electrical Characteristics T<sub>c</sub> = 25°C, unless otherwise noted

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_D = 250\mu A$	40	-	-	V
Gate-Body Leakage Current		Igss	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
Zero Gate Voltage Drain Current	T <sub>J</sub> =25°C	I <sub>DSS</sub>	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V	-	-	1	μА
	T <sub>J</sub> =55°C			-	-	5	
Gate-Threshold Voltage		V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0	1.5	2.5	V
Drain-Source on-Resistance <sup>2</sup>		_	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	4.8	6.6	
		R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A	-	5.9	8.8	mΩ
Forward Transconductance	2	<b>g</b> fs	V <sub>DS</sub> = 5V, I <sub>D</sub> = 5A	-	28	-	S
Dynamic Characteristic	s					•	
Input Capacitance	out Capacitance C <sub>iss</sub>		-	3310	-		
Output Capacitance  Reverse Transfer Capacitance		Coss	$V_{DS} = 15V, V_{GS} = 0V, f = 1MHz$	-	280	-	pF
		Crss		-	209	-	
Switching Characteristi	cs						,
Total Gate Charge		Qg		-	20.5	-	nC
Gate-Source Charge Gate-Drain Charge		Q <sub>gs</sub>	$V_{GS} = 4.5 \text{V}, V_{DD} = 20 \text{V}, I_{D} = 10 \text{A}$	-	5.9	-	
		$Q_{gd}$		-	9.7	-	
Turn-on Delay Time		t <sub>d(on)</sub>		-	15.4	-	. nS
Rise Time Turn-off Delay Time Fall Time		tr	$V_{GS} = 10V, V_{DD} = 15V,$	-	9.0	-	
		t <sub>d(off)</sub>	$R_G = 3.3\Omega, I_D = 1A$	-	76	-	
		t <sub>f</sub>		-	7.1	-	
Drain-Source Body Dio	de Charac	teristics					
Diode Forward Voltage <sup>2</sup>		V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	-	1.0	V
Continuous Source Current <sup>1,5</sup>		Is	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	-	-	75	Α

#### Note:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300 \text{us}$  , duty cycle  $\leq 2\%$
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =42A.
- 4.The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



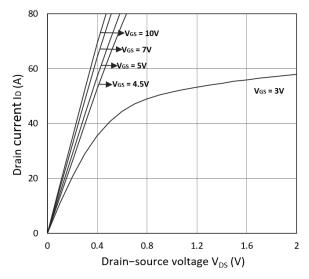


Figure 1. Output Characteristics

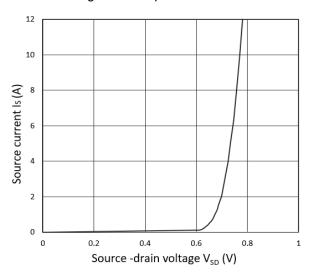


Figure 3. Forward Characteristics of Reverse

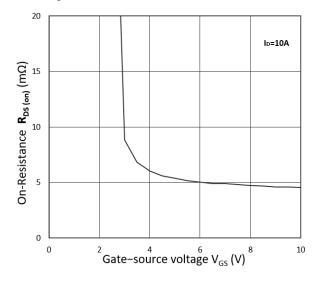


Figure 5. RDS(on) vs. VGS

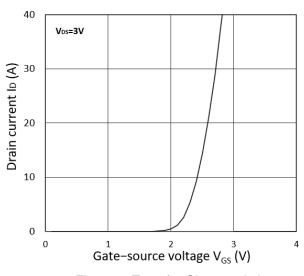


Figure 2. Transfer Characteristics

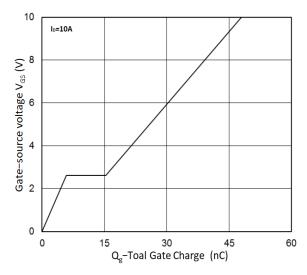


Figure 4. Gate Charge Characteristics

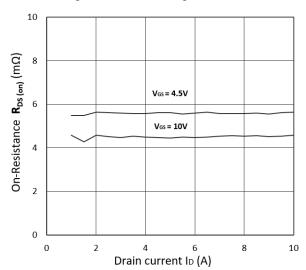


Figure 6.  $R_{DS}(on)$  vs.  $I_{D}$ 



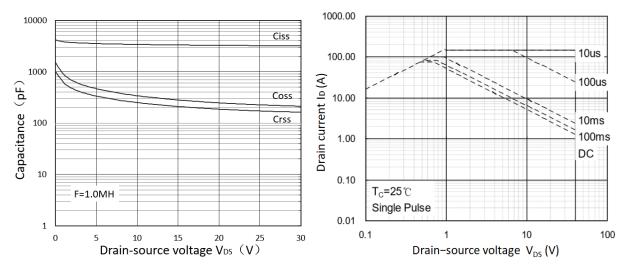


Figure 7. Capacitance Characteristics

Figure 8. Safe Operating Area

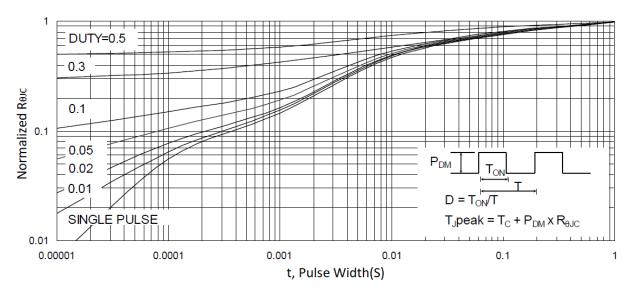


Figure 9. Normalized Maximum Transient Thermal Impedance

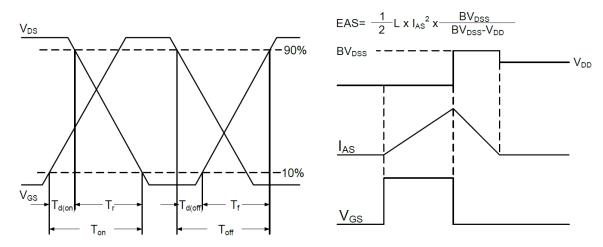


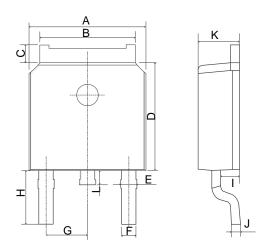
Figure 10. Switching Time Waveform

Figure 11. Unclamped Inductive Switching

Waveform



### **Mechanical Dimensions for TO-252**



## **COMMON DIMENSIONS**

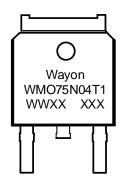
	MM			
SYMBOL	MIN	MAX		
Α	6.40	6.80		
В	5.13	5.50		
С	0.88	1.28		
D	5.90	6.22		
E	0.68	1.10		
F	0.68	0.91		
G	2.29REF			
Н	2.90REF			
I	0.85	1.17		
J	0.51REF			
K	2.10	2.50		
L	0.40	1.00		



### **Ordering Information**

Part	Package	Marking	Packing method
WMO75N04T1	TO-252	WMO75N04T1	Tape and Reel

### **Marking Information**



WMO75N04T1 = Device code WWXX XXX= Date code

#### **Contact Information**

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